PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Soon Hyun PARK	12/15/2010
Won Sang CHOI	12/15/2010
Tae Hyun SUNG	12/15/2010
Jeong Eun OH	12/15/2010
Jong Hak LEE	12/15/2010

RECEIVING PARTY DATA

Name:	LG ELECTRONICS INC.	
Street Address:	20 Yeouido-dong Yeongdeungpo-gu	
City:	Seoul	
State/Country:	REPUBLIC OF KOREA	
Postal Code:	150-721	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29381698

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NAME OF SUBMITTER:	James T. Eller Jr.

PATENT REEL: 025535 FRAME: 0489

PATENT

293

Total Attachments: 2

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PATENT REEL: 025535 FRAME: 0490

BIRCH, STEWART, KOLASCH & BIRCH, LLP

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ASSIGNMENT

	Application No. 29/381,698	<u> </u>	Filed December 22, 2010	
Insert Name(s) of Inventor(s)	***(Given Name FAMILY NAME (ALL CAPS))***			
	WHEREAS,	Mr. Soon Hyun PARK	; Mr. Won Sang CHOI	
	Mr. Tae Hyun SUNG	Ms. Jeong Eun OH	. Mr. Jong Hak LEE	
		:		
	***************************************	,	,	
	•	<u> </u>	•	
		•	,	
			<u></u>	
Insert Title	(hereinafter designated as the u	undersigned) has (have) invented certai	n new and useful improvements in	
of Invention				
	for which an application for L undersigned (except in the case	etters Patent of the United States of A of a provisional application).	merica has been executed by the	
Insert Date of Signing of Application	December 15, 2010; December 15, 2010; on December 15, 2010; October 15, 2010; and October 15, 2010 respectively ; a			
Insert Name of Assignee	WHEREAS,	ELECTRONICS INC.		
Insert Address of Assignee	of	Yeongdeungpo-gu Seoul 150)-721 Republic of Korea	
C HECK BOX F APPROPRIATE	its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and in any foreign countries.			
	paid, the receipt of which is h undersigned has (have) sold, transfer unto said Assignee & America, its territories, depend any and all Letters Patent(s)	deration of the sum of Ten Dollars (\$10 dereby acknowledged, and other good assigned and transferred, and by these full and exclusive right to the said in dencies and possessions and the entire which may be granted therefor in the possessions, and if the box above is defined the said in the sa	and valuable consideration, the e presents does sell, assign and nvention in the United States of right, title and interest in and to e United States of America, its	
	and to any and all divisions, reterm or terms for which the same	eissues, continuations, conversions and e may be granted.	d extensions thereof for the full	

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The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree (s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division, conversion or reissue thereof or Letter Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States of America patent(s) or a grant of a valid United States of America and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patents resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Birch, Stewart, Kolasch & Birch, LLP the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

The undersigned hereby covenant(s) that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date _	15/12/2010	Name of Inventor Soon Hyun PARK
Date _	15/12/2010	(signature) Mr. Soon Hyun PARK Name of Inventor
	15/12/2010	(signature) Mr. Won Sang CHOI T. H. S.
		Name of Inventor (signature) Mr. Tae Hyun SUNG
Date_	15/12/2010	Name of Inventor (signature) Ms. Jeong Eun OH
Date _	15/12/2010	Name of Inventor(signature) Mr. Jong Hak LEE
Date _		Name of Inventor(signature)

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June 2002